MSKSEMI















ESD

TVS

TSS

MOV

GDT

PLED

Broduct data sheet

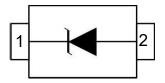


PACKAGE OUTLINE



SOD-323

PIN CONFIGURATION



Feature

- 1400W Peak pulse power per line (t_P = 8/20μs)
- SOD-323 package
- Response time is typically < 1 ns
- Protect one I/O or power line
- Low clamping Voltage
- RoHS compliant
- Transient protection for data lines to IEC61000-4-2(ESD)
 ±30KV(air), ±30KV(contact);

IEC 61000-4-4 (EFT) 40A (5/50ns) 61000-4-5 (Lightning) 70A (8/20us)

Applications

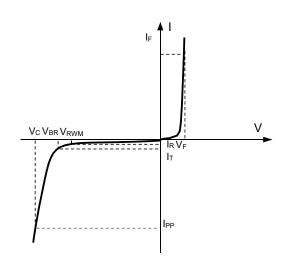
- Cell phone handsets and accessories
- Personal digital assistants (PDA's)
- Notebooks, desktops, and servers
- Portable instrumentation
- Cordless phones
- Digital cameras
- Peripherals

Mechanical Characteristics

- Lead finish:100% matte Sn(Tin)
- Mounting position: Any
- Qualified max reflow temperature:260°C
- Device meets MSL 3 requirements
- Pure tin plating: 7 ~ 17 um
- Pin flatness:≤3mil

Electronics Parameter

Symbol	Parameter
V _{RWM}	Peak Reverse Working Voltage
I _R	Reverse Leakage Current @ V _{RWM}
V_{BR}	Breakdown Voltage @ I⊤
lτ	Test Current
IPP	Maximum Reverse Peak Pulse Current
Vc	Clamping Voltage @ IPP
P _{PP}	Peak Pulse Power
CJ	Junction Capacitance
IF	Forward Current
V _F	Forward Voltage @ I _F





Absolute maximum rating@25 □

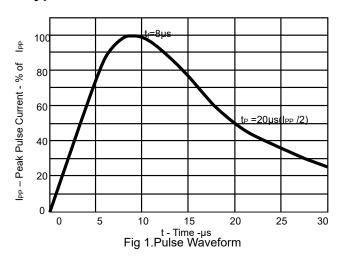
Rating	Symbol	Value	Units
Peak Pulse Power (t₂ = 8/20μS)	P _{pp}	1400	W
Lead Soldering Temperature	T∟	260 (10 sec)	$^{\circ}\! \mathbb{C}$
Operating Temperature	TJ	-55 to 125	$^{\circ}$ C
Storage Temperature	Tstg	-55 to 150	$^{\circ}$ C

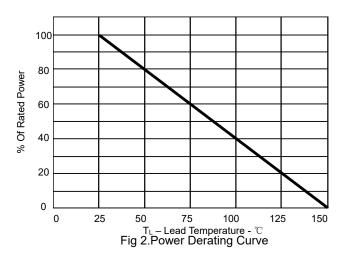
Electrical characteristics per line@25 ℂ (unless otherwise specified)

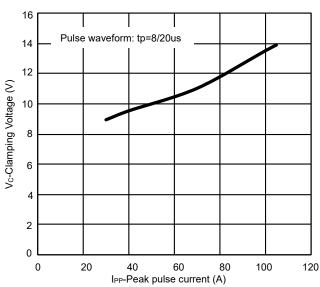
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Units
Peak Reverse Working Voltage	V _{RWM}				4.5	V
Breakdown Voltage	V _{BR}	I _t =1mA	5		7	V
Reverse Leakage Current	IR	V _{RWM} =4.5V			5	μA
Clamping Voltage	Vc	I _{PP} =40A t _P = 8/20µs		9.5	11	V
Clamping Voltage	Vc	I _{PP} =70A t _P = 8/20µs		11	12	V
Clamping Voltage	Vc	I _{PP} =100A t _P = 8/20μs		13.5	15	V
Junction Capacitance	Cj	V _R =0V f = 1MHz	750	850	950	pF



Typical Characteristics







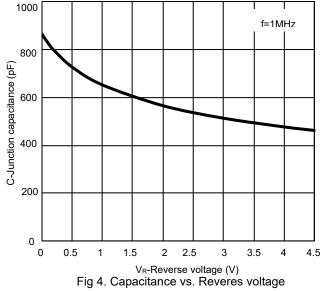
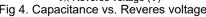
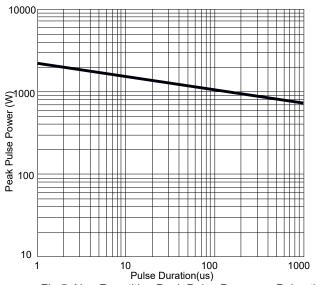


Fig 3. Clamping voltage vs. Peak pulse current





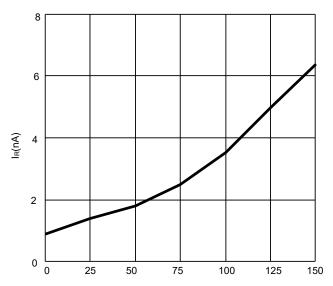


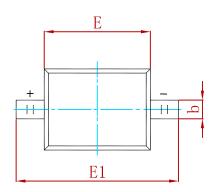
Fig 5. Non Repetitive Peak Pulse Power vs. Pulse time

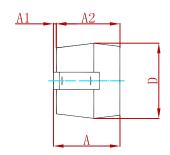
Fig 6. Typical Leakage Current vs. Temperature

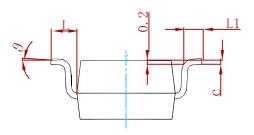




PACKAGE MECHANICAL DATA

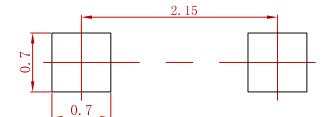






Cumbal	Dimensions In Millimeters		Dimensions In Inches	
Symbol	Min.	Max.	Min.	Max.
Α		1.000		0.039
A 1	0.000	0.100	0.000	0.004
A2	0.800	0.900	0.031	0.035
b	0.250	0.350	0.010	0.014
С	0.080	0.150	0.003	0.006
D	1.200	1.400	0.047	0.055
E	1.600	1.800	0.063	0.071
E1	2.550	2.750	0.100	0.108
L,	0.475 REF.		0.019	REF.
L1	0.250	0.400	0.010	0.016
θ	0°	8°	0°	8°

Suggested Pad Layout



Note:

- 1. Controlling dimension: in millimeters.
- 2.General tolerance:± 0.05mm.
- 3. The pad layout is for reference purposes only.

REEL SPECIFICATION

P/N	PKG	QTY
PTVSHC3D4V5U-MS	SOD-323	3000



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